

# CALL for PAPER



## IMAPS GARDEN STATE – 2007 SPRING SYMPOSIUM & EXHIBITION

Tuesday May 15, 2007

Bell Laboratories - Lucent Technologies, Murray Hill, NJ

**Estimated over 22 Exhibitors / 80 Attendees**

The Garden State Chapter Symposium Technical program committee seeks papers that demonstrate how new technologies and applications are expanding and redefining microelectronics "between the chip and the system". The 2007 Spring Symposium on microelectronics will focus on the areas of Industry, Systems and Applications, Design, and Materials & Process. Abstracts should highlight the major contributions of the work in each of these four areas of concentration.

<p>Symposium Technical Committee Chair:</p> <p style="text-align: center;"><b>Voya Markovich</b></p> <p>Endicott Interconnect Technologies, Inc Office: (607) 755-1978 Fax (607)755-6151</p> <p>Please send your <b>250-300</b> word abstract To : <a href="mailto:voya.markovich@eitny.com">voya.markovich@eitny.com</a></p> <p><i>Please note that the Technical Committee will condense your abstract to one that is approximately 50 words long for <b>marketing</b> purposes. If you prefer to do this personally, then please <b>include</b> the condensed version of the abstract along with the longer version.</i></p>	<p style="text-align: center;"><b>IMAPS 4-TIER PARTICIPATION</b></p>
<p><b>Industry</b></p> <ul style="list-style-type: none"> <li>. Biomedical</li> <li>. Telecom - Microwave</li> <li>. Military Applications</li> <li>. Consumer Electronics</li> <li>. Renewable Energy: Fuel Cells, Solar</li> </ul> <p><b>Systems Packaging/ Applications/ Designs</b></p> <ul style="list-style-type: none"> <li>. EMI/ Signal Integrity/ Electrical Modeling</li> <li>. Thermal and Power Management</li> <li>. Manufacturing, Outsourcing &amp; Quality Assessment</li> <li>. Software and Firmware Applications</li> <li>. High Performance Interconnects and Boards</li> <li>. Imaging Sensors</li> <li>. Micro Packaging - MEMS and Nano Packaging</li> <li>. Emerging Technologies</li> </ul>	<p><b>Advanced Processes &amp; Materials</b></p> <ul style="list-style-type: none"> <li>. 3D packaging and High Density Substrates</li> <li>. Electro-Static Protection</li> <li>. Photonic/ Optoelectronic packaging</li> <li>. Underfill/ Encapsulants and Adhesives</li> <li>. Green packaging / Compliance with RoHS</li> <li>. Flip-Chip and Bumping: Processes, Reliability</li> <li>. Wirebonding and Stud Bumping</li> <li>. Embedded and Integrated Passives</li> <li>. Ceramic, Polymer and Conductive Materials</li> <li>. Cu/ Low-K</li> <li>. LED Packaging</li> </ul> <p><b>Poster Session</b></p> <ul style="list-style-type: none"> <li>. Outstanding papers that do not fit in planned or created sessions will be considered.</li> </ul>

**Please submit before April 3rd, 2007**

Visit us on the Web at [www.imaps-gs.org](http://www.imaps-gs.org)



# IMAPS GARDEN STATE CHAPTER



## IMAPS-GS 2007 SPRING SYMPOSIUM & EXHIBITION

Tuesday, May 15<sup>th</sup> 2007 –  
Bell Laboratories - Lucent Technologies, Murray Hill, NJ

### CORRESPONDING AUTHOR REGISTRATION FORM

Full Name: \_\_\_\_\_  
*Last* \_\_\_\_\_ *First* \_\_\_\_\_ *M.I.* \_\_\_\_\_  
 Title of Paper: \_\_\_\_\_

**IMAPS MEMBER?**      **YES:**       **NO:**       IMAPS Member ID:

Company or Affiliation: \_\_\_\_\_  
 Address: \_\_\_\_\_  
*Street Address* \_\_\_\_\_ *Apt. / Unit #* \_\_\_\_\_  
*City:* \_\_\_\_\_ *State:* \_\_\_\_\_ *ZIP Code* \_\_\_\_\_  
 Country: \_\_\_\_\_

Work Phone:      ( ) \_\_\_\_\_      Cell Phone:      ( ) \_\_\_\_\_  
 Work FAX:      ( ) \_\_\_\_\_

E-mail Address: \_\_\_\_\_

**Please place an X mark next to all organizations of which you are a member**

<b>SMTA</b>	<input type="checkbox"/>	<b>ACerS</b>	<input type="checkbox"/>	<b>IEEE</b>	<input type="checkbox"/>	<b>ASM</b>	<input type="checkbox"/>	<b>SME</b>	<input type="checkbox"/>	<b>SAMPE</b>	<input type="checkbox"/>	<b>Other</b>	<input type="checkbox"/>
If "Other" -which organization?													

Please send your **250-300** word abstract **along** with the above **completed** author registration form as email attachments to [voya.markovich@eitny.com](mailto:voya.markovich@eitny.com)

**Please submit before March 12, 2007**

Visit us on the Web at [www.imaps-gs.org](http://www.imaps-gs.org)